

Description :

- . Low melting point adhesive use for Student Artwork or DIY.

Physical properties and general information :

Raw base material	: Thermoplastic synthetic resin	
Color	: White	
Form	: Glue stick	
Softening point	: 80±4°C	Ring & Ball Method
Viscosity @ 180°C	: 3500mPa · s	TOKI BM Type
@ 160°C	: 6000mPa · s	Viscometer
Application temp.	: Use with hot melt glue gun	
Open time	: 30~35 sec	
Setting time	: 15~20 sec	
Solid content	: 100%	
Storage direction	: Store in cool, dry place	

Notice :

- 1). The temperature of heating should not be over 200°C; it would cause weak bonding due to high temperature heating in long time.
- 2). Try some sample before purchase.
- 3). This description is for reference only.
- 4). Wearing protection during operation.